

Chemical Division

Epoxy-Liquid Injection Molding

Low internal stress injection molding method by liquid epoxy resin



Molding system and materials

FEATURES

- ▶ Caseless packaging
- ▶ Low viscosity molding compounds
- ▶ Low molding pressure*¹
- ▶ Wide range molding temperature*²
- ▶ Alternative encap process of potting method

*¹ Molding pressure: 0.5-4 MPa

*² Molding temperature: 80-160°C


APPLICATIONS

- ▶ Encapsulation of large size devices for industrial equipment
- ▶ Modularize some devices to one component package


Advantages

E-LIM system—alternative potting system

Caseless packaging

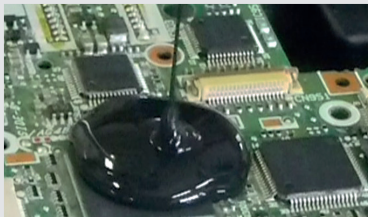


Good permeability



X-section view

Conventional Potting Method



Line-up

- ▶ Liquid molding compounds TCG1450 series

Technical Support

- ▶ “Open Labo” is prepared for your initial molding trials
- ▶ Optimized system structure can be suggested by our project